

**WHAT IS CLAIMED IS:**

1. A door module for a vehicle door comprising:  
a non-structural substrate carrier;  
a door trim panel configured to be coupled to the substrate carrier;  
a door trim interface member integrally molded with the carrier as a single unitary article;  
a carrier interface member extending from the door trim panel;  
wherein the door trim panel is releasably coupled to the carrier by releasable engagement of the door trim interface member and the substrate carrier interface member.
2. The door module of Claim 1 wherein the door trim interface member is a retainer that defines a space for at least partially receiving the carrier interface member.
3. The door module of Claim 2 wherein the retainer is a "U"-shaped loop.
4. The door module of Claim 1 wherein the carrier interface member is a projection that extends from the door trim panel and engages the door trim interface member.
5. The door module of Claim 4 wherein the carrier interface member is a hook extending from the door trim panel.
6. The door module of Claim 1 wherein the carrier interface member is integrally molded with the door trim panel.
7. The door module of Claim 1 wherein the substrate carrier further comprises an integrally molded impact absorber.
8. The door module of Claim 1 wherein the substrate carrier further comprises an integrally molded pull cup support.

9. A method of preparing a module vehicle door for transportation to a location for assembly of a vehicle door, the method comprising:

providing a non-structural carrier and a door trim panel;  
mounting the trim panel to the carrier by engaging a projection on the trim panel with a retainer integrally molded with the carrier.

10. The method of Claim 9 wherein the carrier comprises at least one of integrally molded impact absorber or an integrally molded pull cup support.

11. A method of assembling a vehicle door having a non-structural carrier, a trim panel, and a structural frame, the method comprising:

receiving the carrier and the trim panel at the location for assembly of the vehicle door;

removing the trim panel from the non-structural carrier;  
coupling the carrier to the structural frame; and  
mounting the trim panel to the non-structural carrier

12. The method of Claim 13 further comprising the step of coupling the trim panel to an assembly line fixture when the carrier is coupled to the frame.

13. The method of Claim 11 wherein the step of mounting the trim panel to the carrier comprises engaging the retainer member with the projection.

14. The method of Claim 11 wherein the projection extends from the trim panel and the retainer member is integrally molded with the carrier as a unitary article.

15. A door module for a vehicle door comprising:  
a non-structural substrate carrier having a first interface member and an integrally molded impact absorber;  
a door trim panel configured to be coupled to the substrate carrier and having a second interface member;  
wherein the door trim panel is releasably coupled to the carrier by releasable engagement of the first interface member and the second interface member.

16. The door module of Claim 15 wherein the first interface member comprises a retainer integrally molded with the carrier and defines a space for at least partially receiving the substrate carrier interface member.

17. The door module of Claim 16 wherein the second interface member is a projection that extends from the door trim panel and engages space defined by the retainer.
18. The door module of Claim 15 wherein the first interface member and the second interface member are integrally molded with the door trim panel.
19. The door module of Claim 15 wherein the integrally molded impact absorber comprises an upper integrally molded impact absorber and a lower integrally molded impact absorber.
20. The door module of Claim 19 wherein the upper impact absorber comprises a series of projections extending from the carrier.
21. The door module of Claim 19 wherein the lower impact absorber comprises a plurality of walls.
22. The door module of Claim 15 wherein the substrate carrier further comprises an integrally molded pull cup support.